<table>
<thead>
<tr>
<th>Board No.</th>
<th>Rev.</th>
<th>Copper Layer Name</th>
<th>Copper</th>
<th>S Mask</th>
<th>P Mask</th>
<th>Assembly</th>
<th>Fab Drawing</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMP8407</td>
<td>C</td>
<td>Top</td>
<td>L2</td>
<td>Bot</td>
<td>Bot</td>
<td>Bot</td>
<td>Bot</td>
</tr>
</tbody>
</table>

**Fabrication Details:**
- **Board No.:** PMP8407
- **Rev.:** C
- **Copper Layer Name:** Top L2 Bot
- **S Mask:** Top Bot
- **P Mask:** Top Bot
- **Assembly:** Top Bot
- **Fab Drawing:**

**Additional Information:**
- **Board No.**
- **Date:** 01-02-13
- **Filename:** PMP8407_RevC
- **Engineer:** D Strasser
- **PCB Design:** (Unknown)
- **Modified Date:** (Unknown Date)
- **Software:** PADs v9.3
### Fabrication Chart

<table>
<thead>
<tr>
<th>FINISHED THICKNESS</th>
<th>SILKSCREEN</th>
<th>SOLDERMASK</th>
<th>FINISHED COPPER WEIGHT</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.031</td>
<td>[Layer 1]</td>
<td>[Layer 1]</td>
<td>1 oz.</td>
</tr>
<tr>
<td>0.062</td>
<td>[Layer 2]</td>
<td>[Layer 2]</td>
<td>2 oz.</td>
</tr>
<tr>
<td>0.093</td>
<td>NONE</td>
<td>NONE</td>
<td>OTHER</td>
</tr>
<tr>
<td>0.125</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>DESIGN</th>
<th>TRACE/GAP SPACING</th>
<th>LAYER COUNT</th>
</tr>
</thead>
<tbody>
<tr>
<td>SMD</td>
<td>0.010/0.010</td>
<td>SINGE SIDED</td>
</tr>
<tr>
<td>THRU-HOLE</td>
<td>0.008/0.007</td>
<td>2 LAYER</td>
</tr>
<tr>
<td>MIX</td>
<td>0.006/0.006</td>
<td>4 LAYER</td>
</tr>
<tr>
<td></td>
<td></td>
<td>OTHER</td>
</tr>
</tbody>
</table>

### Notes: Unless Otherwise Specified

1. **Material:** All materials, including but not limited to base laminate, bonding materials and soldermask coatings forming the finished printed circuit board shall meet UL-796 requirements and be RoHS compliant and have a flammability of UL94-V0.

2. **Base Laminate:** Equivalent, Wt./% Cu or higher, minimum decomposition temp. T(d) of 320 deg. C. Glass epoxy resin, copper-cloth in accordance with 2 layer stack-up, compliant with lead-free process.

3. **Soldermask:** Soldermask over bare copper (SMBB) using liquid photo-imageable soldermask in accordance with IPC-SM-840. Color: Green. Minor soldermask adjustments to facilitate PCB fab and or assembly is allowed provided no defects are created to final assembly as a result.

4. **Tolerances:** Unless otherwise specified PCB tolerances shall be +/-0.005 inches, hole diameters shall be +/-0.003 inches.

5. **Plating:** Holes requiring plating, see hole chart, to have 1 oz. (0.0014) min. THK min. Thick Copper.

6. **Finish:** Plate with RoHS compliant, immersion silver preferred, immersion tin or SnAgCu, with SMA flux, 0.0002" to .0005" thick all exposed areas as coated, no active fluxes are acceptable.

7. **Legend:** If required, silkscreen legend(s) with white non-conductive epoxy ink.

8. **Markings:** Board must bear vendor’s identification code (etch or white non-conductive ink). Location optional.

9. **Workmanship:** Board is to be manufactured per IPC-A-600 CLASS 2 requirements or better.

10. **Documentation:** PCB vendor is required to return any and all PCB documents supplied or ultimately purchased by Texas Instruments upon completion of purchase order.

11. **Drill Sizes:** Hole diameters shown are finished sizes after plating unless otherwise noted.

12. **Panel Border:** Any metal in border area including part number, datecode and/or revision letter must be covered with soldermask.

13. **Process Changes:** No dimensional, material, or process changes are allowed without prior explicit written permission from Texas Instruments.
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